

General Description

The WSC15N10 is the highest performance trench N-ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSC15N10 meet the RoHS and Green Product requirement , 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

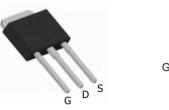
Product Summery

BVDSS	RDSON	ID
100V	80mΩ	15A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter
- Networking DC-DC Power System
- Load Switch

TO-251 Pin Configuration





Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	100	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	15	A
I₀@T₀=100°C	Continuous Drain Current, V _{GS} @ 10V ¹	11	A
I _{DM}	Pulsed Drain Current ²	64	A
EAS	Single Pulse Avalanche Energy ³	30	mJ
I _{AS}	Avalanche Current	6	A
P _D @T _C =25℃	Total Power Dissipation ³	60	W
P _D @T _C =100℃	Total Power Dissipation ³	30	W
T _{STG}	Storage Temperature Range	-55 to 170	°C
TJ	Operating Junction Temperature Range	-55 to 170	°C

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit	
R _{0JA}	Thermal Resistance Junction-ambient ¹		50	°C/W	
R _{θJC}	Thermal Resistance Junction-Case ¹		2.5	℃ /W	

Absolute Maximum Ratings



N-Ch MOSFET

Electrical Characteristics (T_J=25¹C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	100			V
$\triangle BV_{DSS} / \triangle T_J$	BVDSS Temperature Coefficient	Reference to 25 $^\circ\!\!{\rm C}$, I_D = 1mA		0.098		V/℃
Б	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =5A		80	100	mΩ
R _{DS(ON)}		V _{GS} =4.5V , I _D =2A		115	130	mΩ
V _{GS(th)}	Gate Threshold Voltage		1.5	2.0	2.5	V
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	— V _{GS} =V _{DS} , I _D =250uA		-4.57		mV/℃
	Drain Source Lookage Current	V _{DS} =80V , V _{GS} =0V , T _J =25°C			1	uA
I _{DSS}	Drain-Source Leakage Current	V _{DS} =80V , V _{GS} =0V , T _J =55℃			5	
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm20V$, $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =5A		13		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		2	4	Ω
Qg	Total Gate Charge (10V)		12	21	30	
Q _{gs}	Gate-Source Charge	V _{DS} =50V , V _{GS} =10V , I _D =5A	3.4	4.9	6.4	nC
Q _{gd}	Gate-Drain Charge		2.9	5.8	8.7	
T _{d(on)}	Turn-On Delay Time			13	24	
Tr	Rise Time	V_{DD} =30V , V_{GS} =10V , R_{G} =6 Ω		10	19	
T _{d(off)}	Turn-Off Delay Time	I _D =1A , RL=30Ω		32	60	ns ns
T _f	Fall Time			16	30	
Ciss	Input Capacitance	V _{DS} =30V , V _{GS} =0V , f=1MHz		940		
C _{oss}	Output Capacitance			80		pF
C _{rss}	Reverse Transfer Capacitance			50		

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy ⁵	V _{DD} =25V , L=0.5mH , I _{AS} =6A	25			mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
ls	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current			5	А
I _{SM}	Pulsed Source Current ^{2,6}	V _G -V _D -0V, Force Current			64	А
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =5A , T _J =25℃			1.1	V
t _{rr}	Reverse Recovery Time		33	47	61	nS
Qrr	Reverse Recovery Charge	l ⊧=5A , dl/dt=100A/µs , T _J =25℃	61	87	113	nC

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t \leq 10sec.

2.The data tested by pulsed , pulse width $\,\leq\,$ 300us , duty cycle $\,\leq\,$ 2%

3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}\text{=}25V, V_{\text{GS}}\text{=}10V, L\text{=}0.5\text{mH}, I_{\text{AS}}\text{=}6\text{A}$

4.The power dissipation is limited by 150 $^\circ\!\mathrm{C}$ $\,$ junction temperature

5. The Min. value is 100% EAS tested guarantee.

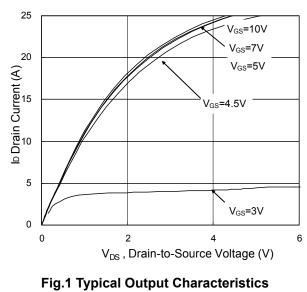
6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



WSC15N10

N-Ch MOSFET

Typical Characteristics



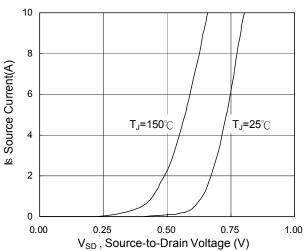


Fig.3 Forward Characteristics Of Reverse

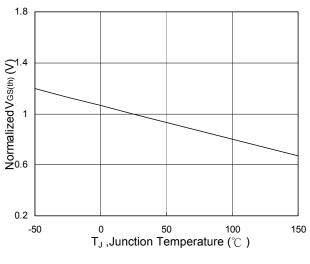


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

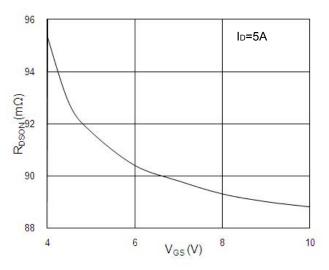


Fig.2 On-Resistance vs. Gate-Source

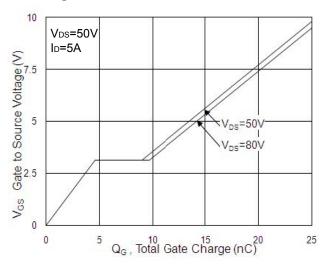
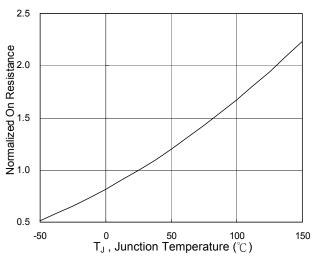


Fig.4 Gate-Charge Characteristics





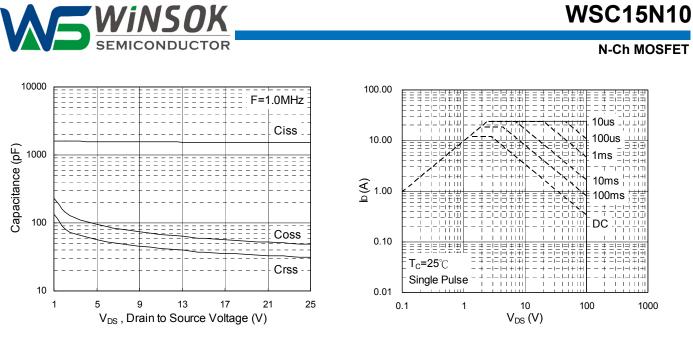




Fig.8 Safe Operating Area

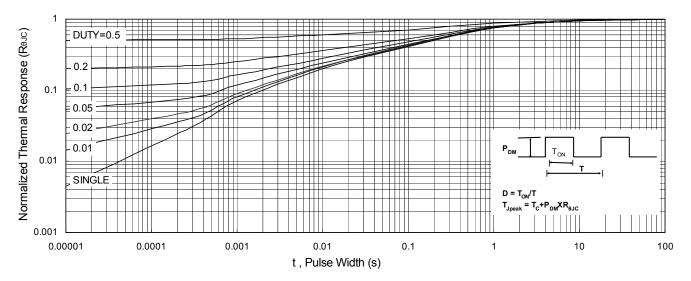
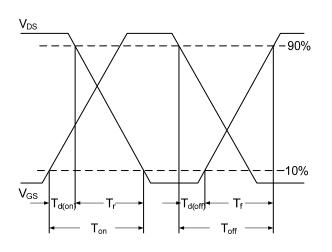
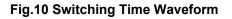


Fig.9 Normalized Maximum Transient Thermal Impedance





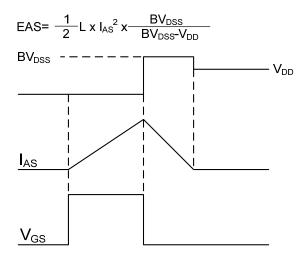


Fig.11 Unclamped Inductive Switching Waveform



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